

REMARKS/ARGUMENT

Minor revisions are being made to clarify page 2. The apparatus claims are being cancelled and replaced with a set of method claims 6-19.

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail to Addressee (mail label # EL924390101US) in an envelope addressed to: U.S. Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on January 8, 2002

Dorothy Jenkins

Name of Person Mailing Correspondence



Signature

January 8, 2002

Date of Signature

Respectfully submitted,



James A. Finder

Registration No.: 30,173

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

JAF:gl

2004-03-01 10:00:00

APPENDIX B
VERSION WITH MARKINGS TO SHOW CHANGES MADE
37 C.F.R. §1.121(b)(iii) and (c)(ii)

SPECIFICATION:

Paragraph at page 2, line 9:

After the shielding case 1 is mounted, there are cases where quality-control testing is performed to determine whether circuits on the circuit substrate 4 properly operate according to design specifications. As a result of the testing, if a circuit mounted on the circuit substrate 4 is not working sufficiently because of a defect found in an electronic component electromagnetically shielded in the shielding case 1, a component-replacement process or some other correction [operations] operation (which is referred to as reworking [as follows) are] in the following) is performed. The reworking is performed such that the shielding case 1 is removed, and the defective electronic component is replaced with a new suitable component.

Paragraph at page 2, line 22:

In the reworking, the shielding case 1 is removed in the following steps. First, all [solders] solder joints fixing the leg sections 3 of the shielding case 1 are simultaneously heated and are melted. Then, in the state where all the [solders] solder joints are melted, the cover section 2 is lifted in the direction in which the cover section 2 will be separated from the circuit substrate 4. In this state, the individual leg sections 3 are pulled out through the through-holes 6 provided on the circuit substrate 4. In this way, the shielding case 1 can be removed from the circuit substrate 4.